

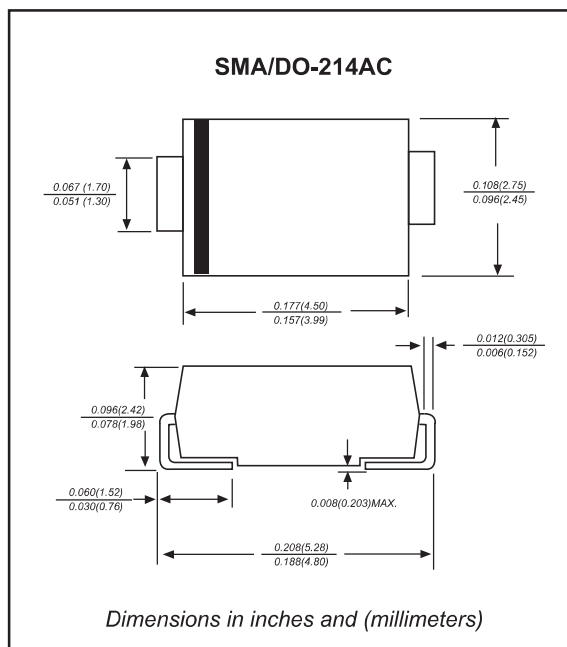
### Features

- ▶ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ▶ Metal silicon junction, majority carrier conduction
- ▶ Low power loss, high efficiency
- ▶ High forward surge current capability
- ▶ High temperature soldering guaranteed:  
260°C/10 seconds
- ▶ Compliant to RoHS Directive 2011/65/EU

### Mechanical data

- ▶ **Case**: JEDEC SMA/DO-214AC molded plastic body
- ▶ **Terminals**: Plated axial leads, solderable per MIL-STD-750, Method 2026
- ▶ **Polarity**: Color band denotes cathode end
- ▶ **Mounting Position**: Any

### Package outline



### Maximum ratings and Electrical Characteristics (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

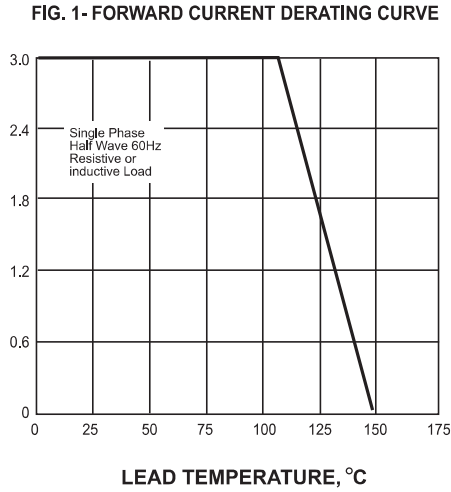
PARAMETER	SYMBOLS	SK34A	UNITS
Maximum repetitive peak reverse voltage	$V_{RRM}$	40	V
Maximum RMS voltage	$V_{RMS}$	28	V
Maximum DC blocking voltage	$V_{DC}$	40	V
Maximum average forward rectified current at $T_L$ (see fig.1)	$I_{(AV)}$	3.0	A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load	$I_{FSM}$	100	A
Maximum instantaneous forward voltage at 3.0A	$V_F$	0.50	V
Maximum DC reverse current $T_A=25^\circ\text{C}$ at rated DC blocking voltage $T_A=100^\circ\text{C}$	$I_R$	0.5 10.0	mA
Typical junction capacitance (NOTE 1)	$C_J$	150	pF
Typical thermal resistance (NOTE 2)	$R_{\theta JA}$	80	$^\circ\text{C}/\text{W}$
Operating junction temperature range	$T_J$	-55 to +150	$^\circ\text{C}$
Storage temperature range	$T_{STG}$	-55 to +150	$^\circ\text{C}$

**Note:**1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.

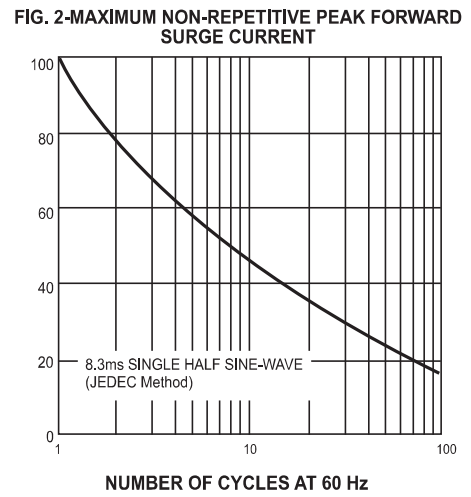
2. P.C.B. mounted with 2.0x2.0" (5.0x5.0cm) copper pad areas

### Rating and characteristic curves

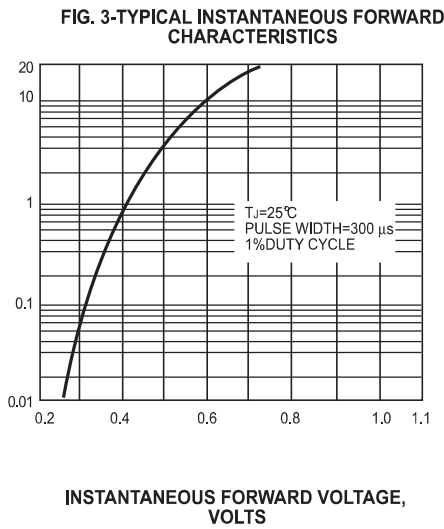
AVERAGE FORWARD RECTIFIED CURRENT,  
AMPERES



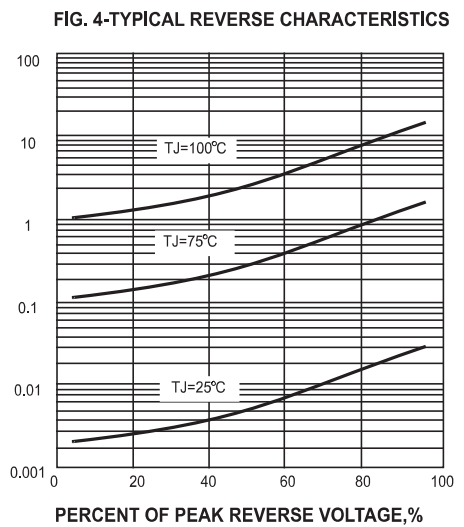
PEAK FORWARD SURGE CURRENT,  
AMPERES



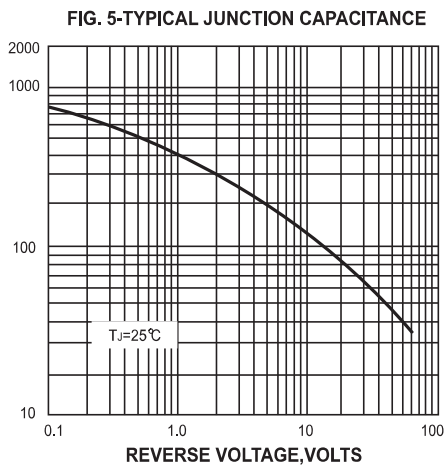
INSTANTANEOUS FORWARD CURRENT,AMPERES



INSTANTANEOUS REVERSE CURRENT,  
MILLIAMPERES



JUNCTION CAPACITANCE, pF



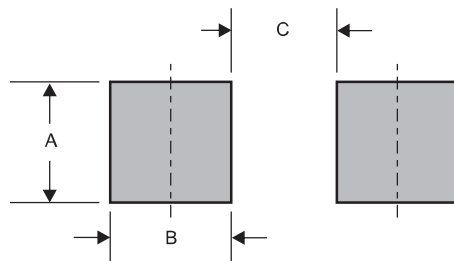
### Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

### Marking

Type number	Marking code
SK34A	SK34A

### Suggested solder pad layout

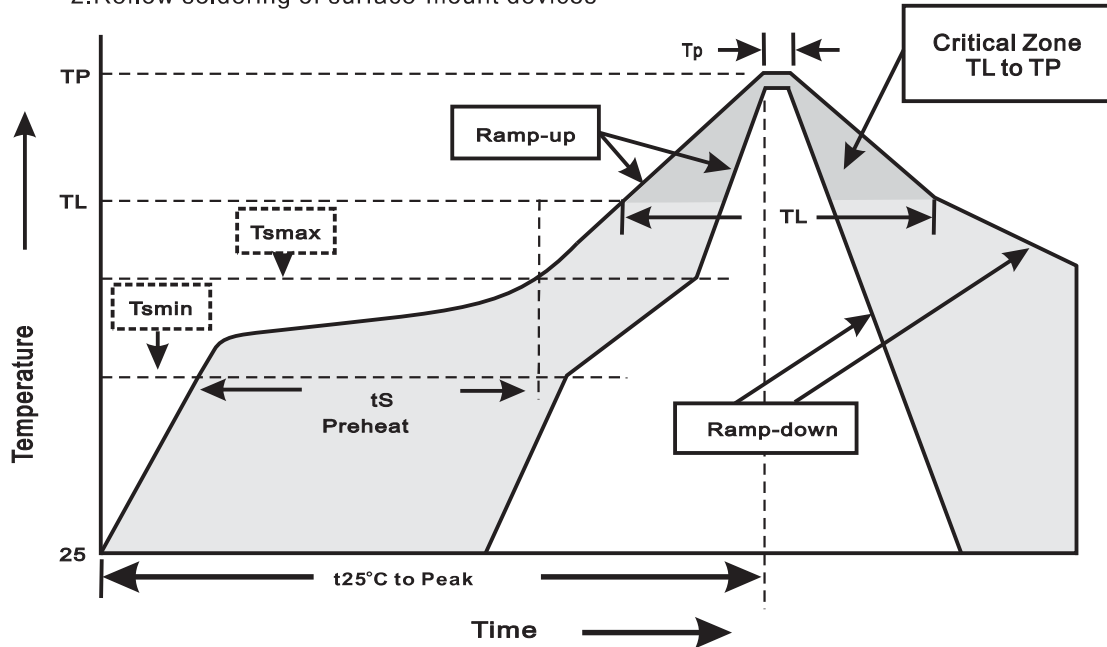


Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SMA	0.110 (2.80)	0.063 (1.60)	0.087 (2.20)

## Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



### 3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(TL to TP)	<3°C/sec
Preheat -Temperature Min(Tsmin) -Temperature Max(Tsmax) -Time(min to max)(ts)	150°C 200°C 60~120sec
Tsmax to TL -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(TL) -Time(tL)	217°C 60~260sec
Peak Temperature(TP)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(tp)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes

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